

A2 --Figure 8 is a side view of a semiconductor device in one step of a prior art semiconductor device manufacturing process that uses a carrier film;--

Please replace page 5, second full paragraph, with the following rewritten paragraph:

A3 --Figure 9 is a side view of a semiconductor device in one step of a prior art semiconductor device manufacturing process that uses flip-chip method; and--

IN THE CLAIMS:

Please delete the non-elected claims 5-7 without prejudice.

REMARKS

Applicant has amended the drawings, title, disclosure and claims. Applicant respectfully submits that the amendments to the drawings, title, disclosure and claims are supported by the application as originally filed and do not contain any new matter. Accordingly, the Office Action will be discussed in terms of the drawings, title, disclosure and claims as amended.

The Examiner has requested that Figs. 7-10 be designated prior art. By the enclosed letter to the Chief Draftsperson submitted for the Examiner's approval, Applicant has designated Figs. 7-10 as prior art.

The Examiner has stated that the title of the invention is misdescriptive. Applicant has provided a new title.

The Examiner has objected to the disclosure. Applicant has amended the disclosure where indicated and respectfully requests that the Examiner withdraw his objection.

The Examiner has rejected rejecting claims 1-4 under 35 USC 103 as being obvious over Barber in view of Kleffner et al., stating that Barber discloses each of the leads 17 is provided with a projection being formed with guided surfaces that are inclined surfaces, but fails to disclose that each one of the bumps is provided with a recess in a surface thereof that faces each of the leads; Kleffner et al. discloses a bump 22 located within a recess; and it would have been obvious to one of ordinary skill in the art to modify Barber to include a bump located within a recess as disclosed by Kleffner et al.

In reply thereto, Applicant respectfully submits that, as is admitted by the Examiner, none of the bumps of Barber includes a recess in a surface thereof that faces each of the leads. Clearly, this is an element of Applicant's claim 1 which is not shown by Barber.

Applicant has carefully reviewed Kleffner et al. and respectfully submits that, as is admitted by the Examiner, Kleffner et al. discloses a bump located within a recess but does not disclose a recess in the bump, an element of Applicant's claimed invention.

In view of the above, therefore, Applicant respectfully submits that the combination suggested by the Examiner is not Applicant's invention and claims 1-4 are not obvious over Barber in view of Kleffner et al.

Attached hereto is a marked-up version of the changes made to the title, specification and claims by the current amendment. The attached page is captioned "Version with markings to show changes made."

In view of the above, therefore, it is respectfully requested that this Amendment be entered, favorably considered and the case passed to issue.

Please charge any additional costs incurred by or in order to implement this Amendment or required by any requests for extensions of time to KODA & ANDROLIA DEPOSIT ACCOUNT NO. 11-1445.

Respectfully submitted,

KODA & ANDROLIA

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I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office Fax No. (703) 308-7722 on September 19, 2002.

William L. Androlia

Name

9/19/2002

Signature

Date

Application Serial No. 09/998,467

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE TITLE OF THE INVENTION:

Delete the title and substitute therefor --A SEMICONDUCTOR DEVICE
HAVING BUMPS --.

IN THE SPECIFICATION:

Page 2, line 6, delete "SUMMARY OF THE INVENTUION" to --SUMMARY OF THE
INVENTION--.

Page 4, last paragraph, has been amended as follows:

Figure 7 is a top view of a semiconductor device in one step of a prior art semiconductor
device manufacturing process that uses a carrier film;

Page 5, first full paragraph, has been amended as follows:

Figure 8 is a side view of a semiconductor device in one step of a prior art semiconductor
device manufacturing process that uses a carrier film;

Page 5, second full paragraph, has been amended as follows:

Figure 9 is a side view of a semiconductor device in one step of a prior art semiconductor
device manufacturing process that uses flip-chip method; and

IN THE CLAIMS:

Delete the non-elected claims 5-7 without prejudice.